

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.3003	100.0	3.2
			Subtotal	0.3003	100	3.2
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00516	2.0	0.055
	Lead alloy	Silver (Ag)	7440-22-4	0.00645	2.5	0.06875
	Lead alloy	Lead (Pb)	7439-92-1	0.24646	95.5	2.62625
			Subtotal	0.25807	100	2.75
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01399	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.04726	100.0	0.50364
			Subtotal	0.06125	200	0.65274
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03763	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01129	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03763	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.54473	99.77	400.0777
			Subtotal	37.63128	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.85134	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.9403	10.0	63.3
	Filler	Silica fused	60676-86-0	50.49255	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11881	0.2	1.266
			Subtotal	59.403	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34609	100.0	25
			Subtotal	2.34609	100	25
			Total	99.99999	100	1065.60274

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.